# Nch 20V 150mA Small Signal MOSFET

V <sub>DSS</sub>	20V
R <sub>DS(on)</sub> (Max.)	2.0Ω
I <sub>D</sub>	±150mA
P <sub>D</sub>	100mW

### Features

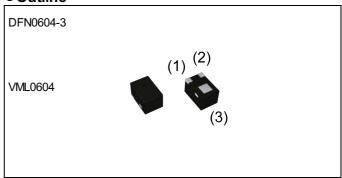
- 1) Ultra Small Package (0.6×0.4×0.36mm)
- 2) Low voltage drive (1.5V) makes this device ideal for portable equipment.
- 3) Drive circuits can be simple.
- 4) Built-in ESD Protection Diode.

## Application

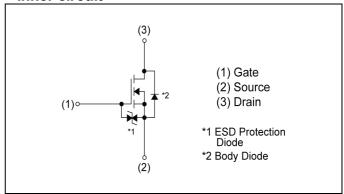
Switching

Level shifter

### Outline



### •Inner circuit



Packaging specifications

Туре	Packing	Embossed Tape
	Reel size (mm)	180
	Tape width (mm)	8
	Basic ordering unit (pcs)	8000
	Taping code	T2CL
	Marking	RY

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	20	V
Continuous drain current	I <sub>D</sub> *1	±150	mA
Pulsed drain current	I <sub>DP</sub> *2	±600	mA
Gate - Source voltage	$V_{GSS}$	±10	V
Power dissipation	P <sub>D</sub> *3	100	mW
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

### ●Thermal resistance

Parameter	Symbol	Values			Lleit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	R <sub>thJA</sub> *3	-	ı	1250	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatav	Cymah al	Symbol Conditions		Values			
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	$\frac{\Delta V_{(BR)DSS}}{\Delta T_i} I_D = 1 \text{mA}$ referenced to 25°C		29	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V	-	-	1	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$	ı	-	±10	μA	
		$V_{DS} = 10V, I_{D} = 100\mu A$	0.3	1	0.8		
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = 10V, I_{D} = 100\mu A$ $T_{a} = -25^{\circ}C$	-	-	0.840	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta  V_{GS(th)}}{\Delta  T_j}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-1.6	-	mV/°C	
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 150mA	-	1.4	2.0		
Static drain - source on - state resistance	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 150mA	-	1.7	2.6	Ω	
		V <sub>GS</sub> = 1.5V, I <sub>D</sub> = 20mA	-	2.7	5.4		

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw≦10µs , Duty cycle≦1%

<sup>\*3</sup> Each therminal mounted on a reference land

<sup>\*4</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
raianietei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	12	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 10V	1	5	1	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	3	-	
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq 10V, V_{GS} = 4.5V$	-	3	-	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 75mA	-	4	-	-
Turn - off delay time	t <sub>d(off)</sub> *4	R <sub>L</sub> ≃ 133Ω	-	12	-	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	25	-	

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Darameter	Cumb of	Conditions	Values			Unit
Parameter	Parameter Symbol Conditions		Min.	Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub> *1	T - 25°C	-	-	80	mA
Pulse forward current	I <sub>SP</sub> *2	T <sub>a</sub> = 25°C	-	-	600	mA
	V <sub>SD</sub> *4	V <sub>GS</sub> = 0V, I <sub>S</sub> = 150mA	-	-	1.2	
Forward voltage		V <sub>GS</sub> = 0V, I <sub>S</sub> = 1mA	-	-	0.800	\/
Forward voltage		$V_{GS} = 0V, I_{S} = 1mA$ $T_{a} = -25^{\circ}C$	-	-	0.900	V

Fig.1 Power Dissipation Derating Curve

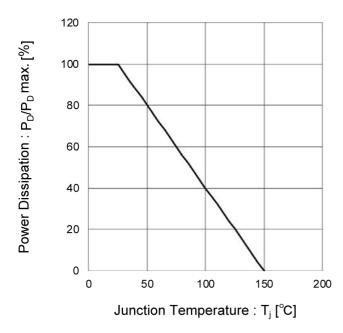


Fig.2 Typical Output Characteristics(I)

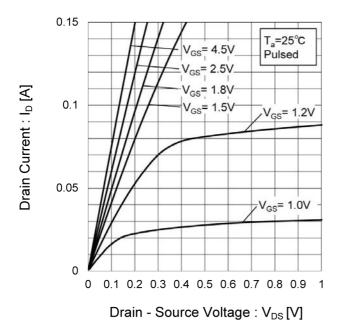
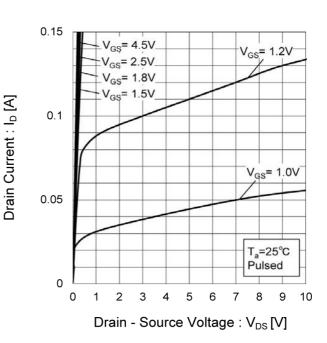


Fig.3 Typical Output Characteristics(II)



Drain-Source Breakdown Voltage: V<sub>(BR)DSS</sub> [V]

Fig.4 Breakdown Voltage vs. Junction Temperature

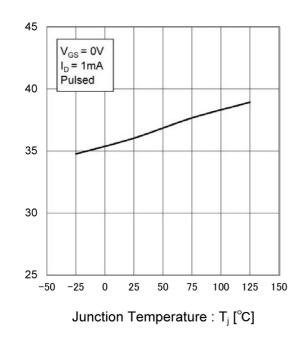


Fig.5 Typical Transfer Characteristics

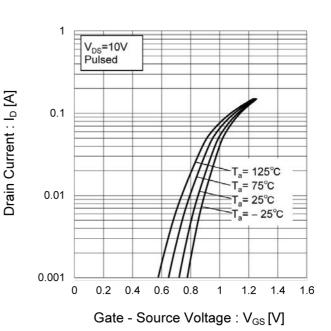


Fig.6 Gate Threshold Voltage vs. Junction Temperature

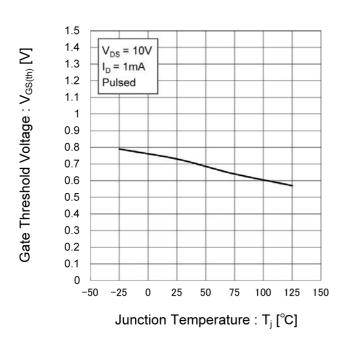


Fig.7 Drain Current Derating Curve

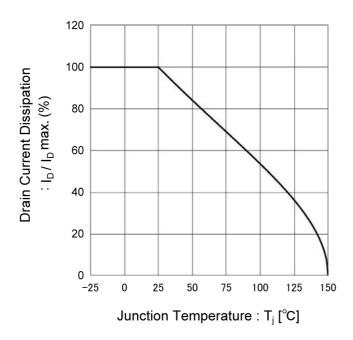
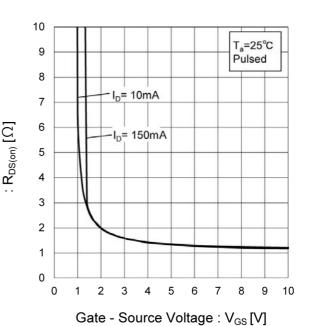


Fig.8 Static Drain - Source On - State Resistance vs. Gate Source Voltage



Static Drain - Source On-State Resistance

Fig.9 Static Drain - Source On - State Resistance vs. Junction Temperature

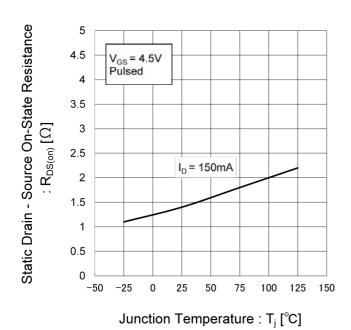


Fig.10 Static Drain - Source On - State Resistance vs. Drain Current(I)

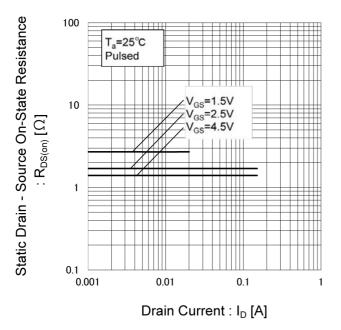


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current(II)

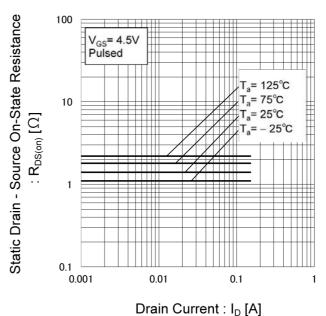


Fig.12 Static Drain - Source On - State Resistance vs. Drain Current(III)

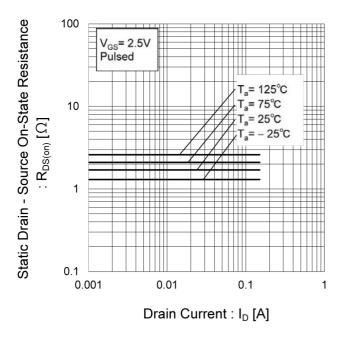


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current(IV)

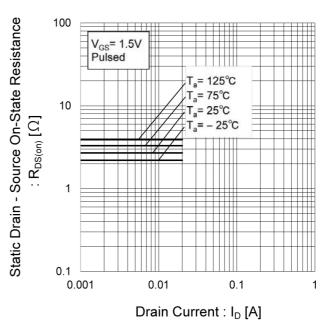
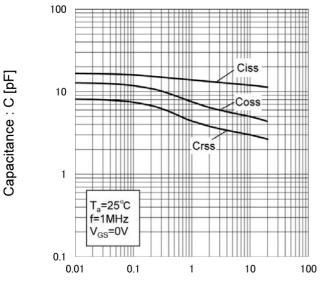
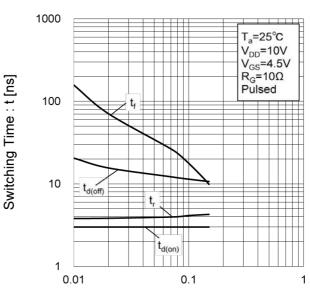


Fig.14 Typical Capacitance vs. Drain - Source Voltage



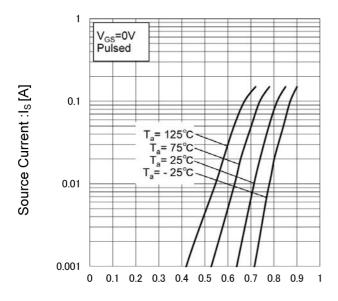
Drain - Source Voltage :  $V_{DS}[V]$ 

Fig.15 Switching Characteristics



Drain Current : I<sub>D</sub> [A]

Fig.16 Source Current vs. Source Drain Voltage



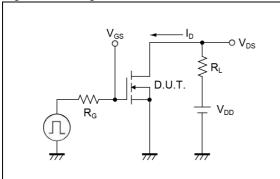
Source-Drain Voltage: V<sub>SD</sub>[V]

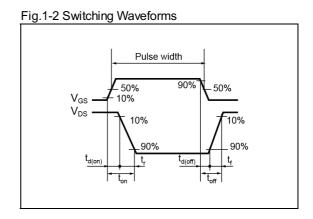


RV3C002UN Datasheet

## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit





### Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

# Dimensions

# DFN0604-3

(VML0604) b1 D ⊕ x S A Α В 3-0 x S B ш e1 □ v □ ± x S B ⊕ x S A е b3 \_ y S ₹ S el b2 е

Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIME	TERS	INCI	HES
DIIVI	MIN	MAX	MIN	MAX
Α	0.33	0.39	0.013	0.015
A1	0.00	0.05	0.000	0.002
b	0.05	0.15	0.002	0.006
b1	0.15	0.25	0.006	0.010
D	0.35	0.45	0.014	0.018
E	0.55	0.65	0.022	0.026
е	0.	30	0.012	
e1	0.	35	0.0	)14
L1	0.07	0.17	0.003	0.007
L2	0.15	0.25	0.006	0.010
X	5#8	0.10	<b>⇔</b> 7	0.004
у	5 <b>4</b> 0	0.10	<b>#</b> 8	0.004
V	5 <b>4</b>	0.05	(#X)	0.002
	VAIL IVAE	TERS	INC	HES

MAX

0.25

0.35

0.27

0.35

MIN

Dimension in mm/inches

MIN

DIM

b2

b3

11

12



MAX

0.010

0.014

0.011

0.014

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(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA
CLASSⅢ	ОГАССШ	CLASS II b	CLASSⅢ
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSIII

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### **Precaution for Mounting / Circuit board design**

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



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